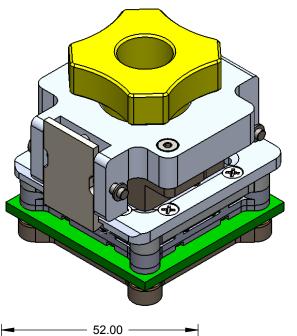
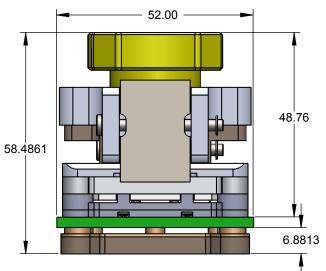
# CBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

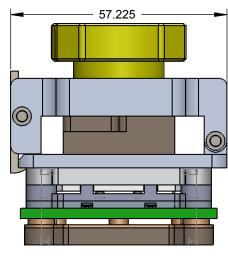


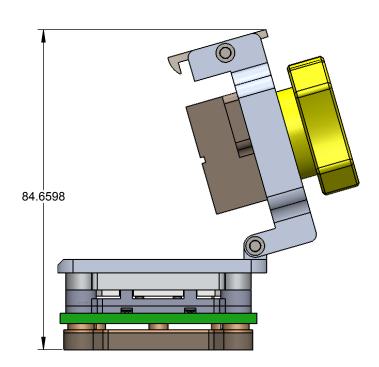
### **Features**

- Wide temperature range (-55C to +180C).
- High current capability (up to 8A).

- Excellent signal integrity at high frequencies.
  Low and stable contact resistance for reliable production yield.
  Highly compliant to accommodate wide co-planarity variations.
- Automated probe manufacturing enables low cost and short







# Description: Custom 31mm CBT spring pin socket, 30x30 array

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

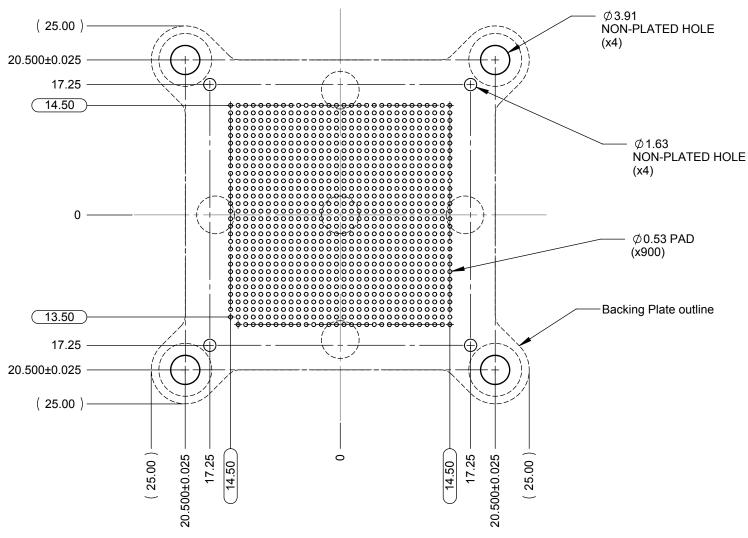
## **CBT-BGA-6009 Drawing**



Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodélectronics.com Material: N/A Finish: N/A Weight: 209.41

STATUS: Released	SHEET: 1 OF 5	REV. B
ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 1:1
FILE: CBT-BGA-6009 Dwg	DATE: 8/23/2012	

# \*Note: BGA pattern centerline is NOT centered with respect to the mounting holes centerline.



Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

## Description: Recommended PCB layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

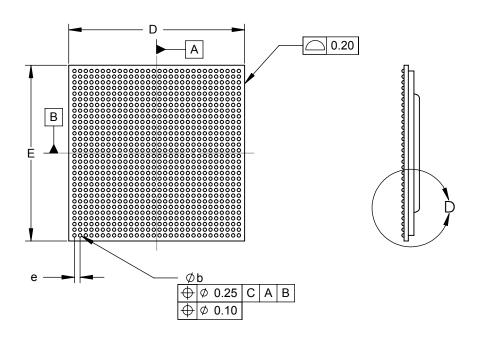
#### **CBT-BGA-6009 Drawing**

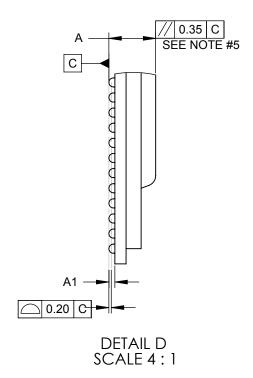


Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: N/A Finish: N/A Weight: 209.41

STATUS: Released	SHEET: 2 OF 5	REV. B
ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 2:1
FILE: CBT-BGA-6009 Dwg	DATE: 8/23/2012	

# Ironwood Package Code: BGA900A





DIM	MIN	MAX
Α	2.9	3.5
A1	0.4	0.6
b	0.5	0.7
D	30.8	31.2
Е	30.8	31.2
е	1.0	
	A A1 b D	A 2.9 A1 0.4 b 0.5 D 30.8 E 30.8

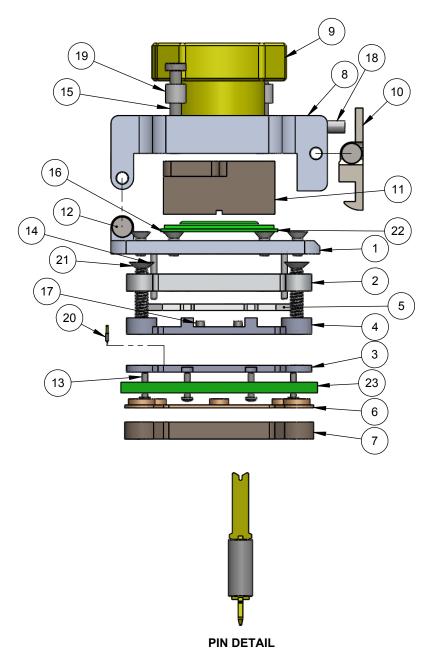
- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

## Description: BGA

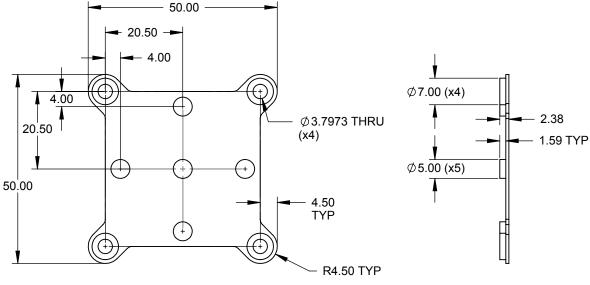
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

CE	CBT-BGA-6009 Drawing Material: N/A		STATUS: Released	SHEET: 3 OF 5	REV. B
	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Weight: 209.41	ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 1:1
			FILE: CBT-BGA-6009 Dwg	DATE: 8/23/2012	



ITEM NO.	DESCRIPTION	QTY.				
1	Upper base for pogo pin socket, custom	1				
2	Custom Socket base, 31mm	1				
3	Custom Socket base, 31mm Bottom Guide 31mm 30X30 array 1mm pitch	1				
4	4 Middle Guide 31mm 30X30 array 1mm pitch					
5	Floating Guide 31mm 30x30 array 1mm pitch	1				
6	custom insulation plate	1				
7	custom backing plate	1				
8	Socket Lid	1				
9	Fluted Knob Compression Screw	1				
10	Latch	1				
11	clamshell compression plate for 31mm custom	1				
12	Hinge Pin and Snap Ring, 3mm OD, 30mm long, 1045 Stl, Blk Oxide	2				
13	Screw, #0-80 x .25", Pan, SS	8 4 2				
14 Dowel Pin. 1/6" x 1/2". SS						
15	Screw, M3 x 12mm, Low Head Cap, SS	2				
16	Flat Hd phillips 4-40 x 5/16" long 82deg hd	8				
17	Floating Guide Spring	8				
Precision Compression Spring, Zinc-Plated Music Wire, 1/2" Length, .12 OD, .016" Wire		1				
19	Spring Clamshell lid assembly	2				
20	Pogo Pin, 1mm Pitch SBT BGA pin	899				
21	100 Deg Flat Head Phillips Machine Screw 300 Series SS, 6-32 Thrd, 3/4" L	4				
22	Customer IC	1				
23	Target PCB	1				



## **INSULATION PLATE DETAIL**

# Description: Skt, Insulation Plate, Pin Det

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

### **CBT-BGA-6009 Drawing**



Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: N/A Finish: N/A Weight: 209.41

STATUS: Released	SHEET: 4 OF 5	REV. B
ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 1:1
FILE: CBT-BGA-6009 Dwg	DATE: 8/23/2012	

## **USER INSTRUCTIONS**

- 1. Place insulating plate, item # 6, and backing plate, item # 7 on the back side of the target PCB.
- 2. Align the socket base assembly, which consists of items 3, 4, 5, 17, 20, 13 & 2 and comes pre-assembled onto target PCB with dowel pins, item # 14.
- 3. Install socket base, item #2, onto the target board with flat head 6-32 machine screws, item # 21. Screws are going thru the target PCB, thru the insulating plate into backing plate.
- 4. Attach socket lid assembly, which consists of items 1,11, 8, 12, 10, 18, 15, 19, 9 (comes pre-assembled) onto socket base with flat head 4-40 machine screws, item # 16. Socket lid assembly is symmetrical and can be attached in any orientation.
- 5. Place IC into the socket.
- 6. Close socket lid, item # 8.
- 7. Turn the compression screw (item #9) until tight hard stops on floating guide (item #5).

Rev	Date	Initials	Description
Α	08/23/12	MR	Original
D	12/06/12	DH	ECO#490; Changed M2816 to M1308.

## **Description: User Instructions**

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	CBT-BGA-6009 Drawing	Material:	STATUS: Released	SHEET: 5 OF 5	REV. B
	Ironwood Electronics, Inc. Tele: (800) 404-0204	Finish: Weight:	ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 1:1
W.	www.ironwoodelectronics.com		FILE: CBT-BGA-6009 Dwg	DATE: 8/23/2012	